

LISTING OF CLAIMS

1.-26. (Cancelled)

27. (Currently Amended) A method of fabricating a micro-mirror structure[[s]] in a micro-mirror strip of micro-mirror structures comprising:

forming a pyramidal structure from a first substrate material; and

defining electrodes on the pyramidal structure for positioning a mirror disposed adjacent to the pyramidal structure.

28. (Original) The method of claim 27, wherein forming the pyramidal structure comprises:

anisotropic etching the pyramidal structure to form steps of various depths in the structure.

29. (Original) The method of claim 27, wherein the electrodes include four electrodes and forming the electrodes further comprises arraigning each electrode on a different one of quadrants of the pyramidal structure.

30. (Original) The method of claim 28, wherein the steps are polygonal in shape.

31. (Currently Amended) The method of claim 27, wherein a second wafer substrate material is bonded to the first substrate material ~~processed wafer.~~

32. (Currently Amended) The method of claim 31, wherein the second substrate material ~~second wafer~~ is a silicon-on-insulator wafer and is bonded to the first substrate material ~~wafer~~ with a device side facing the wafer.

33. (Currently Amended) The method of claim 31, further comprising:

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disposing a material to define ~~the~~ a mirror in a surface of the second substrate material wafer.

34. (Currently Amended) The method of claim 31, further comprising:
defining sensors in the surface of the second substrate material wafer.

35. (Currently Amended) The method of claim 27, further comprising:
adding dam structures to at least one of the substrate materials wafers to isolate the structure from adjacent micro-mirror structures in a strip of micro-mirror structures.

36. (Currently Amended) The method of claim 34, further comprising:
defining other electronic components of the micro-mirror structures in one ~~or the other of~~ the substrate materials wafers.

37. (Withdrawn) A hinge comprising:
a plurality of parallel hinge sections provided by vertical slots therein, the slots and parallel hinge sections being dimensioned to provide vertical and lateral stiffness to and a minimal torsion spring constant for the hinge.

38. (Original) A micro-mirror assembly comprising:
a frame;
an array of two-dimensional deflecting mirrors mounted in the frame; and
dams disposed between the mirrors to block viscous interaction between each of the two dimensional deflecting mirrors and adjacent ones of the two-dimensional mirrors.